No.: RVAC-K-HTS-0001 /3

Date: 2023. 1. 17

Data sheet

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR

TYPE AND HIGH VOLTAGE - ANTI-SULFURATION

Style: RVAC32

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: $+5^{\circ}$ C ~ $+35^{\circ}$ C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipment by the company.

Solderability shall be satisfied.

 Product specification contained in this data sheet are subject to change at any time without notice

• If you have any questions or a Purchasing Specification for any quality agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

/3

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 1/10

1. Scope

1.1 This data sheet covers the detail requirements for fixed thick film chip resistors; rectangular type and high voltage anti-sulfration, style of RVAC32

1.2 Applicable documents

JIS C 5201–1: 2011, JIS C 5201–8: 2014, JIS C 5201–8–1: 2014 IEC60115–1: 2008, IEC60115–8: 2009, IEC60115–8–1: 2014 EIAJ RC–2134 C–2010

2. Classification

Type designation shall be the following form.

(Example)

RVAC	32	_	475	F	TP
1	2	3	4	5	6
Sty	le				

1 Fixed thick film chip resistors; rectangular type and high voltage anti-sulfration

_____ Style

2 Size

3 Temperature coefficient of resistance

K	±100×10 ⁻⁶ / °C
-(Dash)	Standard

4 Rated resistance

475	E24 Series, 3 digit,	Ex. 475> 4.7MΩ
	E96 Series, 4 digit,	
		$1022>10.2k\Omega$

5 Tolerance on rated resistance

n	±0.5%
U	±0.5%
F	±1%
ے	±5%

6 Packaging form

g	
В	Bulk (loose package)
TP	Paner taning

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Rated dissipation (W)	Temperature coefficient of resistance (10 ⁻⁶ /°C)		Rated resistance range(Ω)	Preferred number series for resistors	Tolerance on rated resistance
		I/	⊥100	100~10M	E24, 96	D(±0.5%), F(±1%)
		r :	±100	100~51M	E24	J(±5%)
RVAC32	0.25		±200	47~97.6	E24, 96	D(±0.5%), F(±1%)
		Siailualu	<u> </u>	47~91	E24	J(±5%)

Style	Limiting element voltage(V)	Insulation voltage (V)	Category temperature range (°C)
RVAC32	500	500	<i>–</i> 55~+155

No: RVAC-K-HTS-0001 /3

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 2/10

3.2 Climatic category

55/125/56 Lower category temperature - 55 °C
Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests \pm (5%+0.1Ω) -for short–term tests \pm (1%+0.05Ω)

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

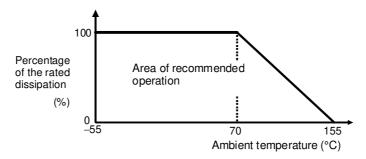


Figure-1 Derating curve

3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

	Symbol	Packaging form		Standard packaging quantity / units
Ī	В	Bulk (loose package)	1,000 pcs.
ſ	TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.

/3

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE - ANTI-SULFURATION RVAC32 Page: 3/10

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure–2 and Table–3.

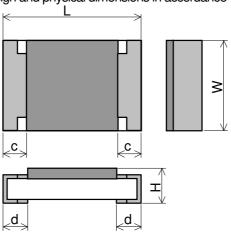


Figure-2

		Tab	le–3		Unit : mm
Style	L	W	Н	С	d
RVAC32	3.1 ± 0.1	1.6 ± 0.15	0.55 ± 0.10	0.5 ± 0.25	0.5 ± 0.25

5.2 Net weight (Reference)

) (
Style	Net weight(mg)
RVAC32	9

6. Marking

The Rated resistance shall be marked in 3 digits (E24) or 4 digits (E96) and marked on over coat side.

• E24 series: 3 digits, E96 series: 4 digits

In case of the resistance value that E96 overlaps with E24, It is marked by either.

Marking example	Contents	Application
123	$12\times10^3 \ [\Omega] \rightarrow 12 \ [k\Omega]$	RVAC32
2R2	2.2 [Ω]	Less than 10Ω of RVAC32
5623	$562\times10^{3} [\Omega] \rightarrow 562[k\Omega]$	RVAC32
12R7	12.7 [Ω]	RVAC32



No: RVAC-K-HTS-0001 /3

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE - ANTI-SULFURATION RVAC32 Page: 4/10

7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

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FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 5/10

Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3 mm	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Final measurements	Sub-clause 4.33.6	No visible damage
		Visual examination	
7	Resistance to soldering heat	Sub-clause 4.18	
		Solder temperature: 260 °C ± 5 °C	
		Immersion time: $10 \text{ s} \pm 0.5 \text{ s}$	
		Visual examination	As in 4.18.3.4
			No sign of damage such as cracks.
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Component solvent	Sub-clause 4.29	
	resistance	Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 2	
		Recovery: 48 h	No visible demons
		Visual examination	No visible damage
	NA	Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
8	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	Adhesion	Test substrate: Figure–3	
	Adriesion	Sub-clause 4.32	
		Force: 5 N	
		Duration: 10 s ± 1 s	No visible damage
	Rapid change temperature	Visual examination	TWO VISIBLE dalflage
	rapid change temperature	Sub-clause 4.19	
		Lower category temperature: –55 °C	
		Upper category temperature: +155 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles. Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
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FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 6/10

Table-4(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	–Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	–Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7	
		The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is the	
		smaller.	
		Duration: 1 min.	No visible damage
		Visual examination	$\Delta R \le \pm (5\% + 0.1\Omega)$
		Resistance	$\Delta \Gamma \geq \pm (576 + 0.152)$
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		(RVC63 may use Alumina substrate.)	
		Test substrate: Figure-3	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C ± 2 °C	
		Duration: 1000 h	
		The voltage shall be applied in cycles of 1.5 h	
		on and 0.5 h.	
		The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is the	
		smaller.	
		Examination at 48 h, 500 h and	
		1000 h:	No visible domage
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$

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FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 7/10

Table-4(4)

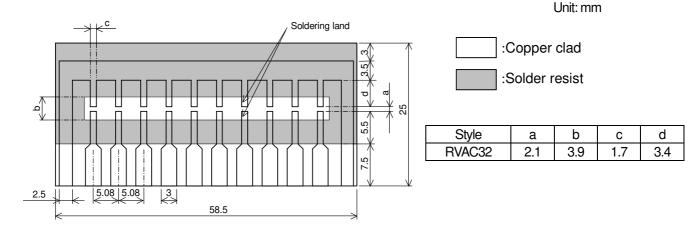
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
11	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Variation of resistance with	Sub-clause 4.8	As in Table–1
	temperature	_55 °C / +20 °C	
		+20 °C / +155°C	
12	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Damp heat, steady state	Sub-clause 4.24	
		Ambient temperature: 40 °C ± 2 °C	
		Relative humidity: $93 \pm \frac{2}{3}$ %	
		a) 1st group: without voltage applied.	
		b) 2nd group: The d. c. voltage shall be applied	
		continuously.	
		The voltage shall be accordance with	
		Sub-clause 4.24.2.1 b). without polarizing	
		voltage [4.24.2.1, c)]	NI. Sala da casa
		Visual examination	No visible damage
			Legible marking
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-3
	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Endurance at upper category	Sub-clause 4.25.3	
	temperature	Ambient temperature:155 °C ± 2 °C	
		Duration: 1000 h	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (5\% + 0.1\Omega)$
14	Humid Sulfur vapor test	ASTM B809	
	(FOS)	Reagent: Sulfur (Saturated vapor)	
		Test temp.: 60°C	
		Relative humidity: 95%RH	
		Test period: 1000h	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$

/3

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 8/10

8. Test substrate



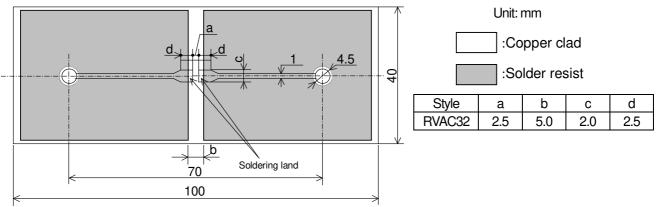
RVAC32 TEST SUBSTRATE

Figure-3

Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.



Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

RVAC32 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

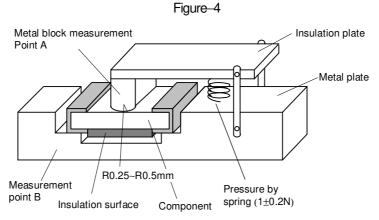


Figure-5

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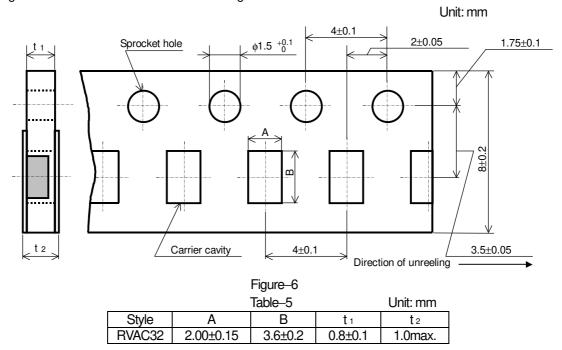
Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 9/10

9. Taping

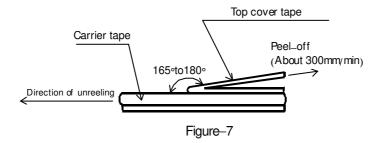
- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.



- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–7.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

 The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.

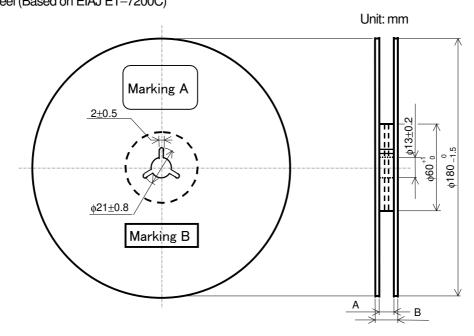


Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND HIGH VOLTAGE

- ANTI-SULFURATION RVAC32 Page: 10/10

9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–8 and Table–6. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

9.4 Leader and trailer tape.

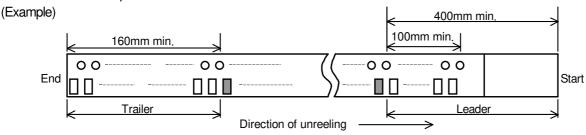


Figure-9

10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)